CLAIMS

What is claimed is:

1. A method for attaching an integrated circuit die to a leadframe, comprising:

(a) fabricating a plurality of integrated circuit die on a wafer;

(b) testing the integrated circuit die on the wafer to determine electrically good integrated circuit die;

(c) producing a wafer map depicting the electrically good integrated circuit die;

(d) disposing an adhesive material onto the electrically good integrated circuit die in accordance with the wafer map;

(e) singulating the integrated circuit die;

(f) adhering the electrically good integrated circuit die to a leadframe;

(g) electrically coupling the good integrated circuit die to a plurality of fingers on the leadframe to form an integrated circuit package; and

(h) excising the integrated circuit package from the leadframe.

2. The method, as set forth in claim 1, comprising the act of encapsulating the integrated circuit package in a molding compound.

3. The method, as set forth in claim 1, comprising the act of grinding the wafer to a desired thickness.

4. The method, as set forth in claim 1, wherein act (d) comprises the act of disposing an adhesive tape onto the electrically good integrated circuit die in accordance with the wafer map.

5. The method, as set forth in claim 1, wherein act (d) comprises the act of disposing an adhesive paste onto the electrically good integrated circuit die in accordance with the wafer map.

6. The method, as set forth in claim 1, wherein act (g) comprises the act of attaching a plurality of wire-bonds between a plurality of bonding pads on the integrated circuit die to a plurality of fingers on the leadframe to form an integrated circuit package.

7. The method, as set forth in claim 1, wherein the acts are performed in the recited order.

8. A method of attaching an integrated circuit die to a substrate comprising:

(a) fabricating a plurality of integrated circuit die on a wafer;

(b) testing the integrated circuit die on the wafer to determine electrically good integrated circuit die;

(c) producing a wafer map depicting the electrically good integrated circuit die;

(d) disposing an adhesive material onto the electrically good integrated circuit die in accordance with the wafer map;

(e) singulating the integrated circuit die;

(f) adhering the good integrated circuit die to a substrate; and

(g) electrically coupling the good integrated circuit die to a plurality of bonding pads on the substrate to form an integrated circuit package.

9. The method, as set forth in claim 8, comprising the act of encapsulating the integrated circuit package in a molding compound.

10. The method, as set forth in claim 8, comprising the act of grinding the wafer to a desired thickness.

11. The method, as set forth in claim 9, comprising the act of disposing a plurality of conductive balls into openings in the molding compound, the openings in the molding compound being correlative to a plurality of conductive pads on the substrate.

12. The method, as set forth in claim 8, wherein act (d) comprises the act of disposing an adhesive tape onto the electrically good integrated circuit die in accordance with the wafer map.

13. The method, as set forth in claim 8, wherein act (d) comprises the act of disposing an adhesive paste onto the electrically good integrated circuit die in accordance with the wafer map.

14. The method, as set forth in claim 8, wherein act (g) comprises the act of attaching a plurality of wire-bonds between a plurality of bonding pads on the integrated circuit die to a plurality of bonding pads on the substrate to form an integrated circuit package.

15. The method, as set forth in claim 8, wherein the acts are performed in the recited order.

16. A method for disposing an adhesive material onto an integrated circuit die comprising:

(a) fabricating a plurality of integrated circuit die on a wafer;

(b) testing the integrated circuit die on the wafer to determine electrically good integrated circuit die;

(c) producing a wafer map depicting the electrically good integrated circuit die; and

(d) disposing an adhesive material onto the electrically good integrated circuit die in accordance with the wafer map.

17. The method, as set forth in claim 16, wherein act (d) comprises the act of disposing an adhesive tape onto the electrically good integrated circuit die in accordance with the wafer map.

18. The method, as set forth in claim 16, wherein act (d) comprises the act of disposing an adhesive paste onto the electrically good integrated circuit die in accordance with the wafer map.

19. A wafer having an adhesive material disposed on only the electrically good integrated circuit dies.

20. A wafer, as in claim 19, wherein the adhesive material comprises an adhesive tape.

21. A wafer, as in claim 19, wherein the adhesive material comprises an adhesive paste.